

ABSTRACT

SUBSTRATE POLISHING APPARATUS

A substrate polishing apparatus includes a polishing table 30 having a polishing surface 10 in the upper surface, a substrate holding portion 31 that holds a substrate W having a surface to be polished in the lower surface, and a holding portion cover 36 that covers the outer side of the substrate holding portion 31. Between the lower portion of the holding portion cover 36 and the upper surface of the polishing table 30, a gap portion for intake 37 is provided, and in the upper portion of the holding portion cover 36, a pipe for exhaust 39 connected to an exhaust mechanism 38 is provided. By operating the exhaust mechanism 38, a rising air current from the gap portion 37 toward the pipe 39 is formed between the outer surface of the substrate holding portion 31 and the inner surface of the holding portion cover 36.

Fig. 4